



NOTES:

1. SUBSTRATE MATERIAL: K170 ALUMINUM NITRIDE (AIN), 0.015 +/- 0.0015 INCHES THICK.
2. METALLIZATION:  
 TOP: 50 MICROINCHES MIN AU OVER 50 MICROINCHES  
 MIN NI OVER 1000 MICROINCHES MIN COPPER.  
 BOTTOM: 30 MICROINCHES MAX AU OVER 50 MICROINCHES  
 MIN NI OVER 1000 MICROINCHES MIN COPPER.
3. CASTELLATIONS ARE 0.015 DIA.
4. ARTWORK CONTROLLED BY ELECTRONIC FILE.